

Corporate Highlights

~7
Elmos ICs
on average in every new car

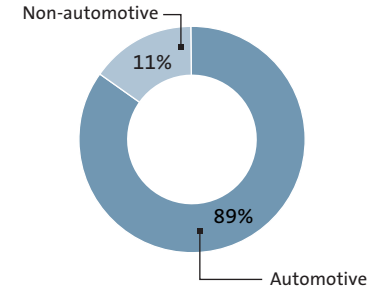
6
product segments:
Ranging, Optical, Sensor ICs,
Motor Control, Lighting,
Safety/Power/Custom ICs

16
locations worldwide
incl. 7 R&D centers
HQ located in Dortmund,
Germany

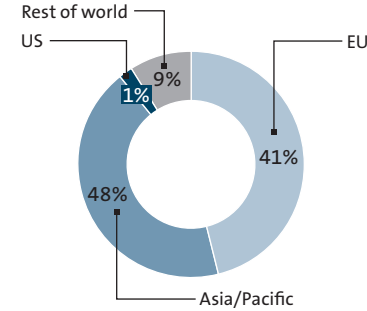
>35
years experience
in analog mixed signal
IC solutions

1,150
employees
thereof 350+
product developers &
engineers

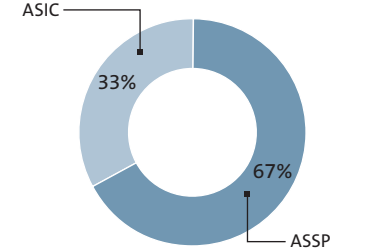
Automotive focused: Sales by industry



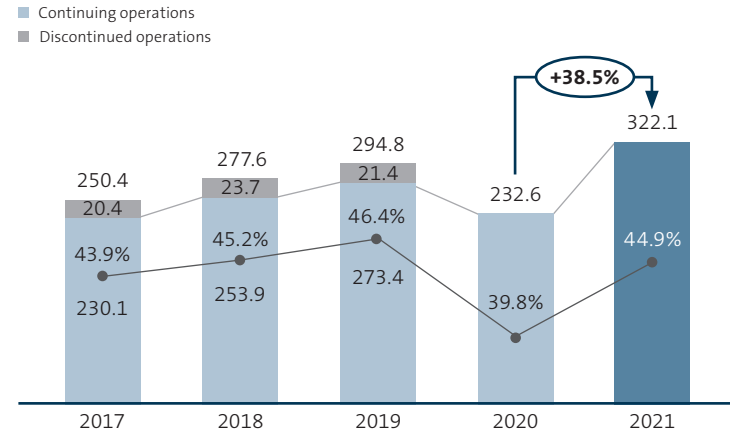
Global presence: Sales by region



ASSP vs. ASIC: in % of sales

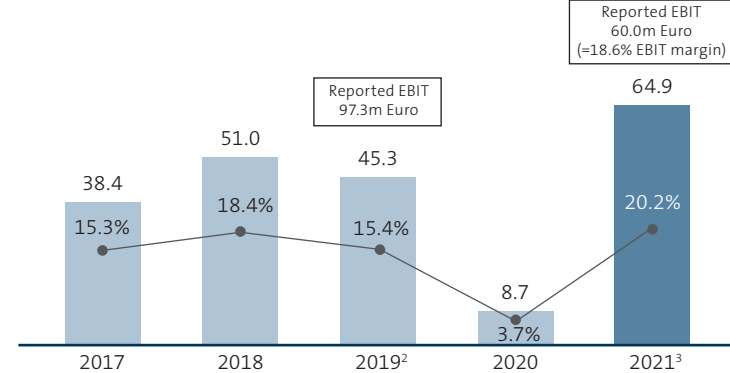


Yearly sales (in million Euro) & gross margin¹ (in %)



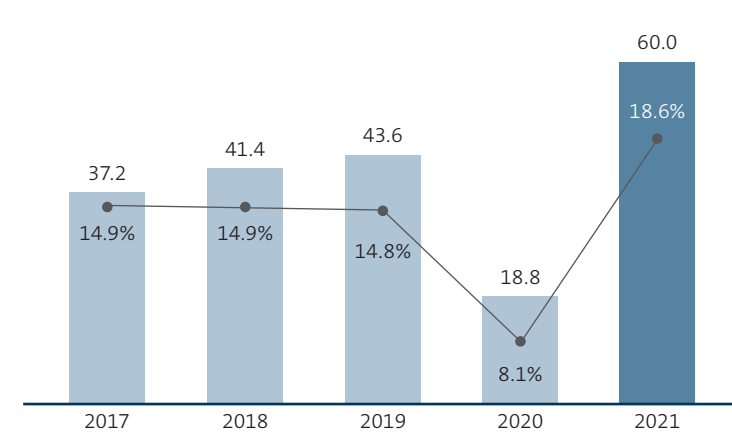
¹ Gross margins in years 2017 to 2019 relate to continuing and discontinued operations; from year 2020 on to continuing operations only.

Yearly EBIT¹ (in million Euro) & EBIT margin¹ (in %)



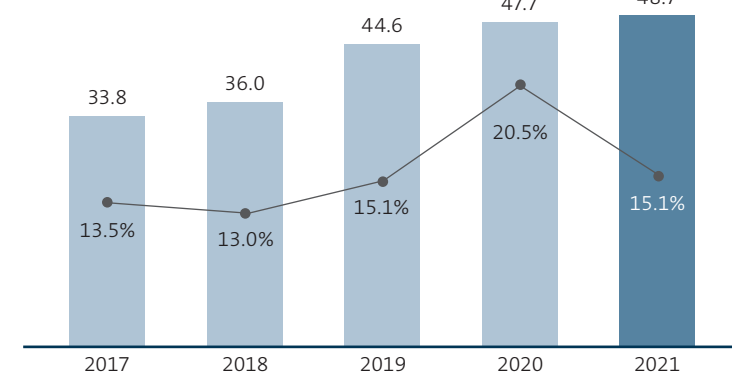
¹ EBIT and EBIT margins in years 2017 to 2019 relate to continuing and discontinued operations; from year 2020 on to continuing operations only.
² Operating EBIT/EBIT margin without consideration of the result from the sale of the subsidiary SMI and without deduction of the restructuring expenses for the termination of the cooperation with the Fraunhofer Institute IMS.
³ Operating EBIT/EBIT margin without consideration of expenses in connection with the agreement on the sale of the wafer fab.

CAPEX^{1,2} (in million Euro & in % of sales)



¹ Capital expenditures for intangible assets and property, plant and equipment less capitalized development expenses.
² CAPEX and R&D expenses in years 2017 to 2019 relate to continuing and discontinued operations; from year 2020 on to continuing operations only.

R&D expenses¹ (in million Euro & in % of sales)

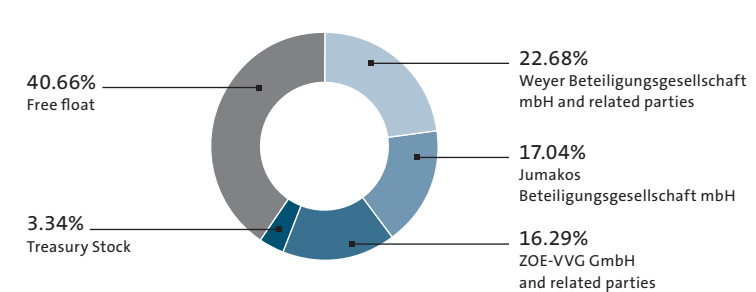


¹ CAPEX and R&D expenses in years 2017 to 2019 relate to continuing and discontinued operations; from year 2020 on to continuing operations only.

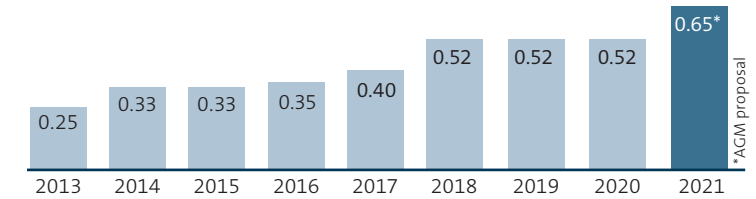
Share price development from January 2021 until December 2021



Shareholder structure as of December 31, 2021



Dividend per share in Euro



*ACM proposal

Basic information

Company foundation	1984
IPO	October 11, 1999
ISIN / WKN	DE0005677108 / 567710
Ticker symbol	ELG
Admission segment	Prime Standard, Regulated Market
Designated sponsor	M.M. Warburg & Co. KGaA
Share capital	17,700,000 Euro/shares

Analysts' coverage (as of March 2022)

Institution	Research Analyst
Deutsche Bank	Robert Sanders
Hauck & Aufhäuser	Christian Sandherr
Oddo BHF	Stéphane Houri
Warburg Research	Malte Schaumann

Financial calendar 2022

Final results 2021 ¹	03/17/2022
Quarterly results Q1/2022 ¹	05/05/2022
Annual General Meeting	05/11/2022
Quarterly results Q2/2022 ¹	08/02/2022
Quarterly results Q3/2022 ¹	11/03/2022

¹ The German Securities Trading Act (Wertpapierhandelsgesetz) and the Market Abuse Regulation (EU) oblige issuers to immediately announce any information that may have a substantial price impact, irrespective of the communicated schedules. Therefore it is possible that we will announce key figures of quarterly and annual results ahead of the dates listed above. As we can never rule out changes of dates, we recommend checking dates and news ahead of schedule on the Company's website (www.elmos.com).

Investor Relations Contact

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www.elmos.com | invest@elmos.com

Key figures | 3-year overview

in million Euro or %	FY 2019		FY 2020	FY 2021
	<i>continuing & discontinued operations</i>	<i>continuing operations</i>		
Sales	294.8	273.4	232.6	322.1
growth in %	6.2%	7.7%	-14.9%	38.5%
<i>thereof continuing operations</i>	273.4	273.4	232.6	322.1
<i>thereof discontinued operations</i>	21.4	n/a	n/a	n/a
Gross profit	136.8	125.6	92.6	144.7
in % of sales	46.4%	45.9%	39.8%	44.9%
R&D expenses	44.6	40.7	47.7	48.7
in % of sales	15.1%	14.9%	20.5%	15.1%
EBIT	97.3 45.3 ¹	29.8 40.9 ²	8.7	60.0 64.9 ³
in % of sales	33.0% 15.4% ¹	10.9% 15.0% ²	3.7%	18.6% 20.2% ³
Consolidated net income after non-controlling interests	85.7	18.5	6.4	39.8
in % of sales	29.1%	6.8%	2.8%	12.4%
Earnings per share (basic) in Euro	4.36	0.94	0.35	2.24
	12/31/2019	12/31/2020	12/31/2021	
Total assets	439.5	395.5	418.0	
Shareholders' equity	339.7	310.2	300.2	
in % of total assets	77.3%	78.4%	71.8%	
Financial liabilities	49.1	45.6	76.1	
Net cash/net debt (-)	74.3	40.2	-10.0	
	FY 2019	FY 2020	FY 2021	
Operating cash flow	45.6	27.3	79.6	
Capital expenditures ⁴	43.6	18.8	60.0	
in % of sales ⁴	14.8%	8.1%	18.6%	
Adjusted free cash flow ⁵	76.9	3.6	11.1	
Dividend per share in Euro	0.52	0.52	0.65 ⁶	

¹ Without consideration of the result from the sale of the subsidiary SMI and without consideration of the restructuring expenses for the termination of the cooperation with the Fraunhofer Institute IMS.

² Without consideration of the restructuring expenses for the termination of the cooperation with the Fraunhofer Institute IMS.

³ Without consideration of expenses in connection with the agreement on the sale of the wafer fab.

⁴ Capital expenditures for intangible assets and property, plant and equipment less capitalized development expenses.

⁵ Cash flow from operating activities less capital expenditures for/plus disposal of intangible assets and property, plant and equipment (incl. payments for additions to shares/proceeds from changes in the scope of consolidation).

⁶ Proposal for the AGM in 2022.

Management Board

DR. ARNE SCHNEIDER

CEO – Chief Executive Officer

- Board member since 2014, appointed until 2025
- Graduate economist
- Strategy, Coordination of Board Responsibilities, Executive Personnel, Quality, Finance, Management Accounting, Investor Relations, Human Resources, Purchasing, IT



GUIDO MEYER

COO – Chief Operating Officer

- Board member since 2017, appointed until 2024
- Graduate engineer (FH)
- Production, Foundry, Assembly, Logistics, Product Engineering

DR. JAN DIENSTUHL

CSO – Chief Sales Officer

- Board member since 2019, appointed until 2023
- Graduate electrical engineer
- Sales, Development, Business Lines, Technology



For a Better Tomorrow



State-of-the-art **ULTRASONIC SENSORS**
enable ADAS and autonomous driving



Dynamic **REAR LIGHT**
presenting unparalleled design opportunities for styling and road safety



Intelligent **THERMAL MANAGEMENT**
solutions for efficient e-mobility



Customized **AMBIENT LIGHTING**
connecting to user emotions: styling, wellbeing and comfort



Touchless **GESTURE RECOGNITION**
for enhanced user-experience



Enhanced **SOFTWARE SOLUTIONS**
for a smarter and more efficient mobility